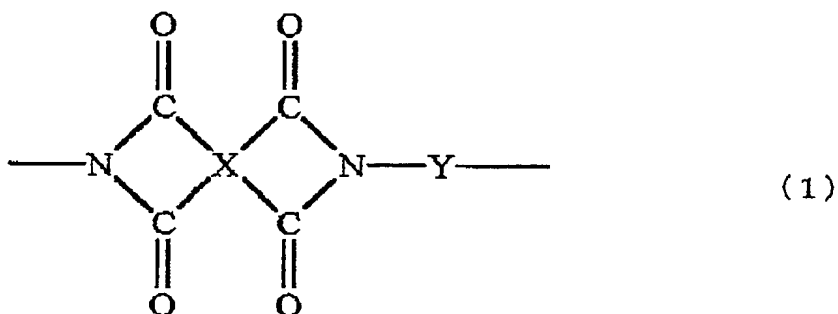
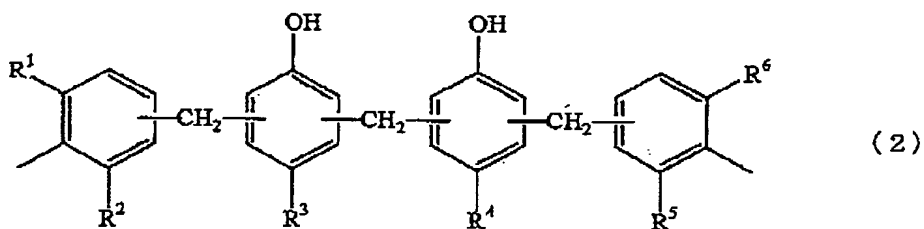


CLAIMS

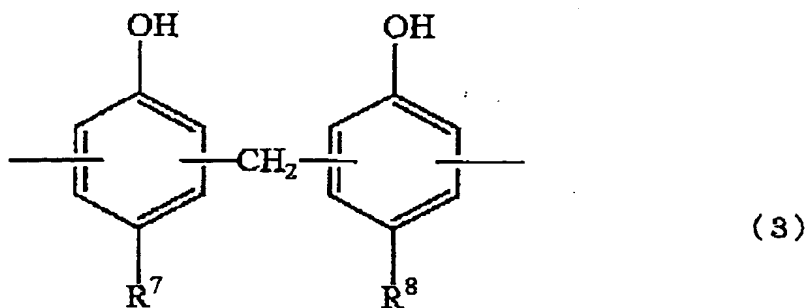
1. A colorless and transparent thermosetting polyimidesilicone resin comprising structural units of the following general formula (1) and structural units of the general formula (4), said resin being soluble
5 in an organic solvent



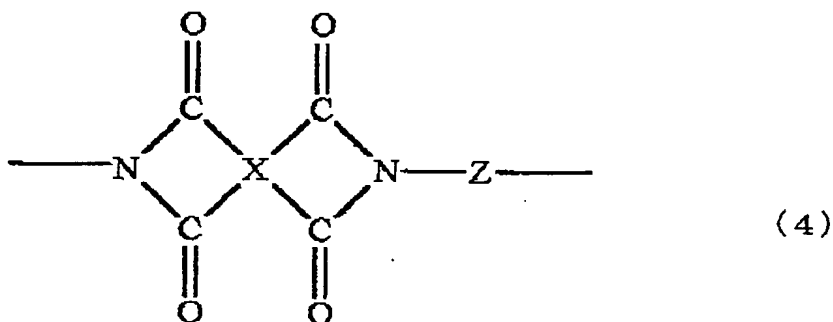
- wherein X is a tetravalent organic group having 4 or more carbon atoms,
10 none of the carbon atoms of X being bound to a plurality of carbonyl groups, and Y is a diamine residue of the general formula (2) or (3),



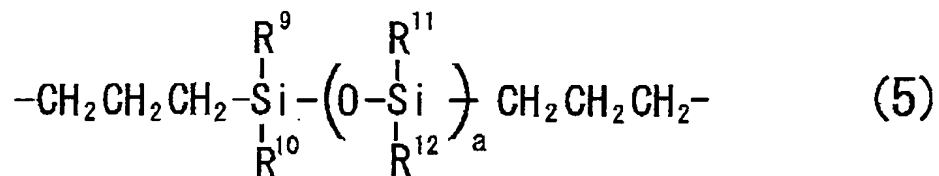
- wherein each of R¹, R², R³, R⁴, R⁵ and R⁶ is independently selected
15 from the group consisting of a hydrogen atom and alkyl groups having 1 to 6 carbon atoms,



wherein each of R^7 and R^8 is independently selected from the group consisting of a hydrogen atom and alkyl groups having 1 to 6 carbon
 5 atoms;



wherein X is a tetravalent organic group having 4 or more carbon atoms,
 none of the carbon atoms of X being bound to a plurality of carbonyl
 10 groups, and Z is a diamine residue of the general formula (5),



wherein each of R^9 , R^{10} , R^{11} , and R^{12} is independently selected from

the group consisting of substituted or unsubstituted monovalent hydrocarbon groups having 1 to 8 carbon atoms, and "a" is an integer of from 1 to 100.

- 5 2. The polyimidesilicone resin according to claim 1, wherein an amount of the diamine residue of the general formula (2) or (3) ranges from 5 mole % to 95 mole % and an amount of the diamine residue of the general formula (5) ranges from 5 mole % to 95 mole %, based on the total amount of the diamine residues.

10

3. The polyimidesilicone resin according to claim 1 or 2, wherein the resin has a transmittance of 80 % or higher in the wavelength region of from 400 nm to 700 nm, measured in a form of a film of 10 μ m thickness on a glass substrate of 1 mm thickness.

15

4. A semiconductor device or a display apparatus which comprises polyimidesilicone resin according to any one of claims 1 to 3 is used.